



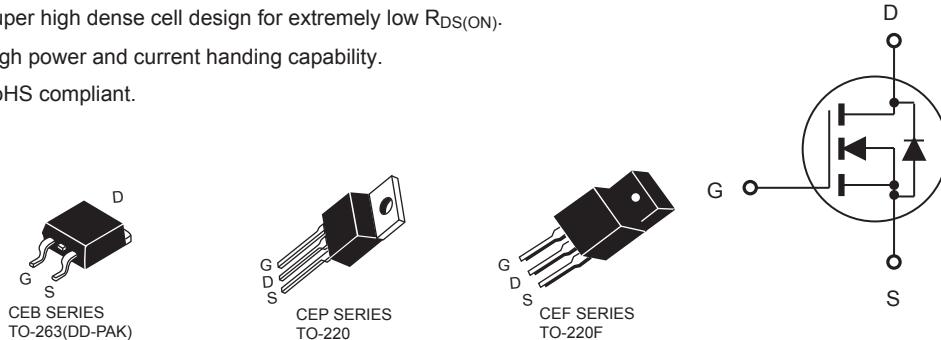
# CEP200N15/CEB200N15 CEF200N15

## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

Type	V <sub>DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub>	@V <sub>GS</sub>
CEP200N15	150V	4.6mΩ	192A	10V
CEB200N15	150V	4.6mΩ	192A	10V
CEF200N15	150V	4.6mΩ	192A <sup>d</sup>	10V

- Super high dense cell design for extremely low R<sub>DS(ON)</sub>.
- High power and current handing capability.
- RoHS compliant.



### ABSOLUTE MAXIMUM RATINGS T<sub>C</sub> = 25°C unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	V <sub>DS</sub>	150		V
Gate-Source Voltage	V <sub>GS</sub>	± 20		V
Drain Current-Continuous @ T <sub>C</sub> = 25°C @ T <sub>C</sub> = 100°C	I <sub>D</sub>	192	192 <sup>d</sup>	A
		122	122 <sup>d</sup>	A
Drain Current-Pulsed <sup>a</sup>	I <sub>DM</sub> <sup>e</sup>	768	768 <sup>d</sup>	A
Maximum Power Dissipation @ T <sub>C</sub> = 25°C - Derate above 25°C	P <sub>D</sub>	357	89	W
		2.85	0.71	W/°C
Single Pulsed Avalanche Energy <sup>h</sup>	E <sub>AS</sub>	720		mJ
Single Pulsed Avalanche Current <sup>h</sup>	I <sub>AS</sub>	60		A
Operating and Store Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150		°C

### Thermal Characteristics

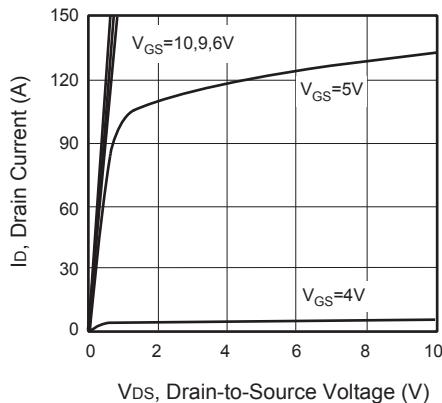
Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	0.35	1.4	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62.5	65	°C/W



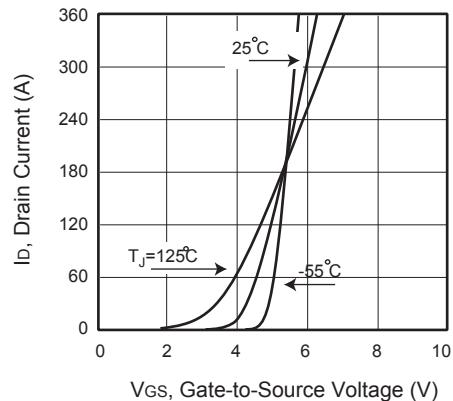
# CEP200N15/CEB200N15 CEF200N15

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

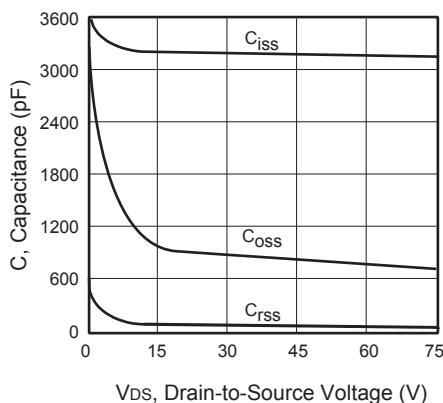
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	150			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 150\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics</b> <sup>b</sup>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		3.8	4.6	$\text{m}\Omega$
<b>Dynamic Characteristics</b> <sup>c</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 75\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		3190		pF
Output Capacitance	$C_{\text{oss}}$			730		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			15		pF
<b>Switching Characteristics</b> <sup>c</sup>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 75\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 10\Omega$		30		ns
Turn-On Rise Time	$t_r$			25		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			80		ns
Turn-Off Fall Time	$t_f$			46		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 75\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$		64		nC
Gate-Source Charge	$Q_{\text{gs}}$			18		nC
Gate-Drain Charge	$Q_{\text{gd}}$			12		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$ <sup>f</sup>				192	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 20\text{A}$ <sup>g</sup>			1.5	V
<b>Notes :</b>						
a.Repetitive Rating : Pulse width limited by maximum junction temperature .						
b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$ . Duty Cycle $\leq 2\%$ .						
c.Guaranteed by design, not subject to production testing.						
d.Limited only by maximum temperature allowed .						
e.Pulse width limited by safe operating area .						
f.Full package $I_{\text{S}(\text{max})} = 96\text{A}$ .						
g.Full package $V_{\text{SD}}$ test condition $I_S = 96\text{A}$ .						
h. $L = 0.4\text{mH}, I_{\text{AS}} = 60\text{A}, V_{\text{DD}} = 50\text{V}, R_G = 25\Omega$ , Starting $T_J = 25^\circ\text{C}$ .						



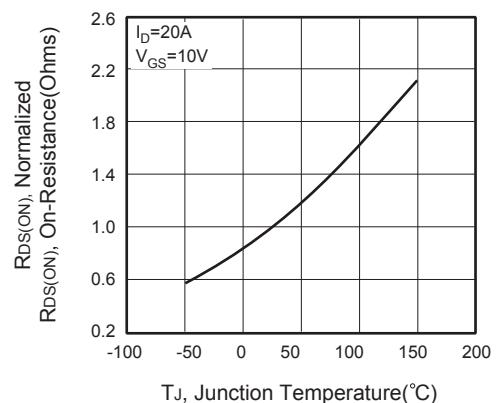
**Figure 1. Output Characteristics**



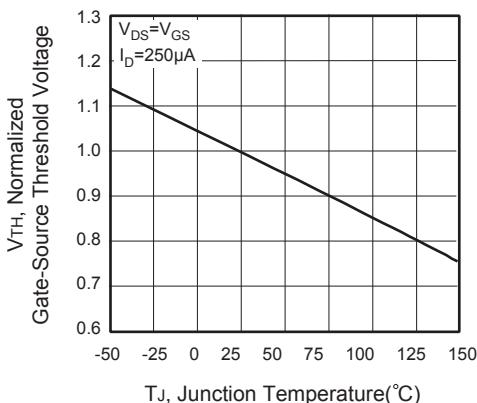
**Figure 2. Transfer Characteristics**



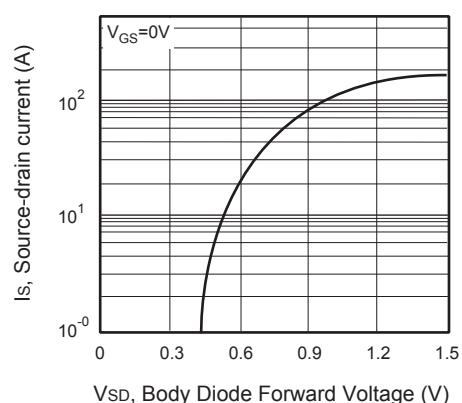
**Figure 3. Capacitance**



**Figure 4. On-Resistance Variation with Temperature**



**Figure 5. Gate Threshold Variation with Temperature**



**Figure 6. Body Diode Forward Voltage Variation with Source Current**



# CEP200N15/CEB200N15 CEF200N15

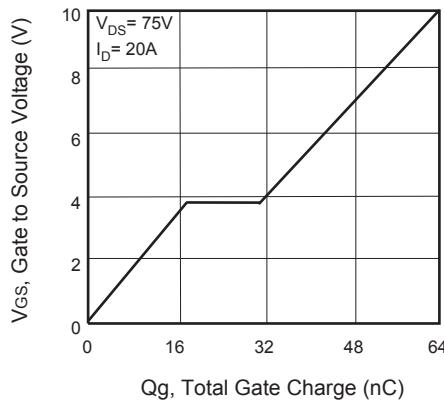


Figure 7. Gate Charge

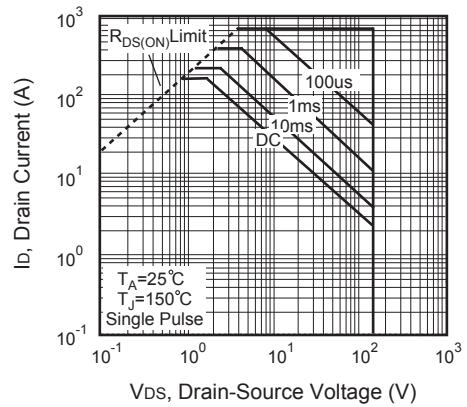


Figure 8. Maximum Safe  
Operating Area

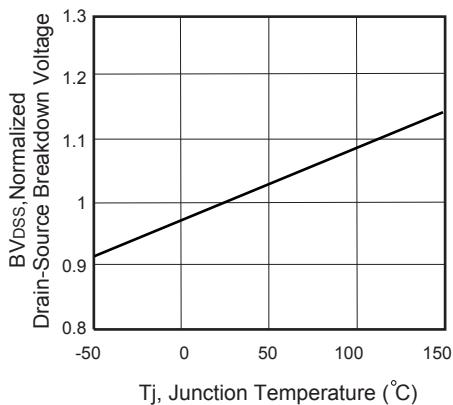


Figure 9. Breakdown Voltage Variation  
VS Temperature

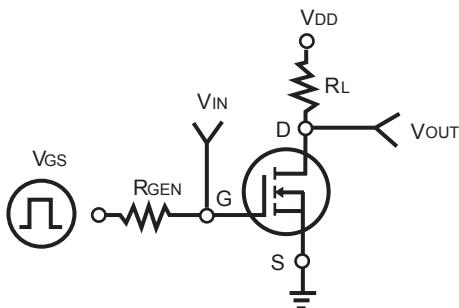


Figure 10. Switching Test Circuit

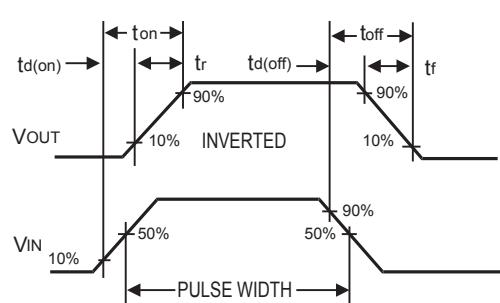
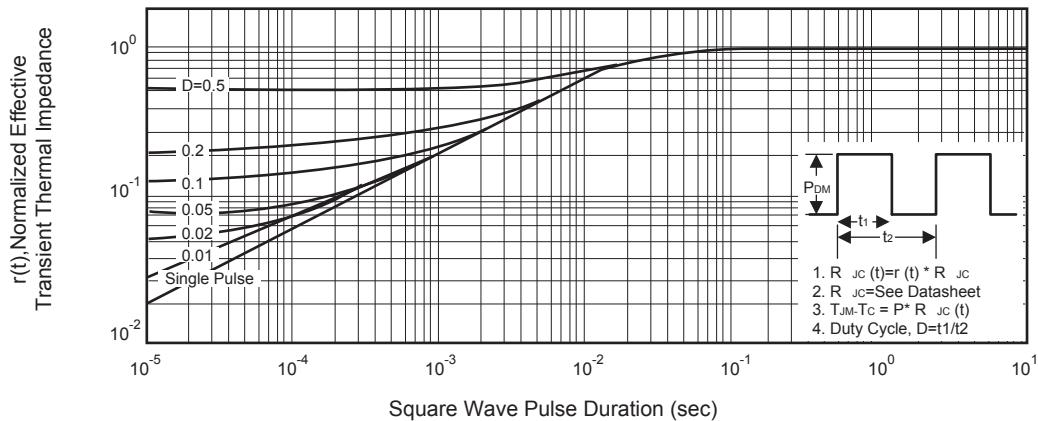


Figure 11. Switching Waveforms

**Figure 12. Normalized Thermal Transient Impedance Curve**